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(71) Applicant: **NANYANG TECHNOLOGICAL UNIVERSITY** [SG/SG]; 50 Nanyang Avenue, Singapore 639798 (SG).

(72) Inventors: **NG, Youce Nigel**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG). **GOH, Guo Liang**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG). **YEONG, Wai Yee**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG). **LIM, Shan De**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG).

(74) Agent: **CHINA SINDA INTELLECTUAL PROPERTY PTE LTD**; 133 Cecil Street #12-01A Keck Seng Tower, Singapore 069535 (SG).

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(54) Title: WIRE EMBEDDING METHOD FOR 3D PRINTING

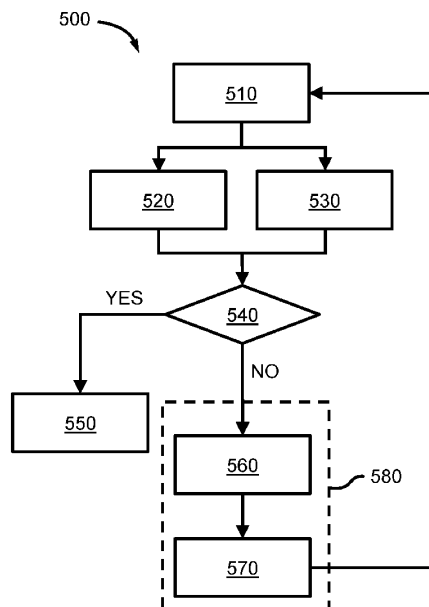


Fig. 3

(57) Abstract: A wire embedding method and system for 3D printing. The method includes: extruding the wire in an extrusion direction via a nozzle towards a substrate surface of the substrate; concurrently with the extruding of the wire, displacing the nozzle in a pull-away direction away from the substrate surface to form an exposed length of the wire between the substrate surface and the nozzle, wherein the exposed length of the wire is formed without the exposed length of the wire contacting the substrate surface; providing a cooling phase; and forming a surface embedded length of the wire using the exposed length of the wire in a surface embedding phase.

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